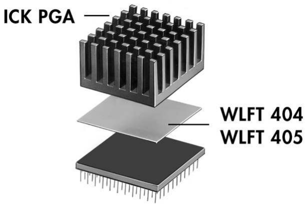
Data sheet Product ICK PGA 21 x 21



Heatsinks and active heatsinks for processors>Heatsinks for PGA
53,3 x 53,3 x 16,5 mm, for IC design PGA and others

Features

way of fixation:	• **therm. conductive foil** • **therm. cond. adhesive**
socket:	**universal**
suitable for processor type:	**universal**
width:	**53.34 mm**
height:	**16.51 mm**
plate thickness:	**5 mm**
length:	**53.34 mm**
thermal resistance:	**7 - 1.9 K/W**
dissipation loss:	**8.6 W**
surface:	**black anodised**

Technical Drawing